

QMJU2.E182327 - Coatings for Use on Recognized Printed Wiring Boards - Component

Coatings for Use on Recognized Printed Wiring Boards - Component

GuangDong SQ UV Curing Materials Co.,Ltd

E182327

8 Dehua Road, Industrial Park

Chengdong Neighborhood Committee, Decheng Street, Deqing County

Zhaoqing, Guangdong 526600 China

Mtl Dsg	Coating Material			Flame Class	Laminate ANSI Type	Min Thk mm	Assembly Solder		Solder Limits	
	Color	Min Thk mic	Max Thk mic				Temp °C	Process Cycles	Process Temp °C	Time sec
Resist coatings for use on Recognized printd wiring boards. Furnished as: two component liquid										
PS-100/PS-100H	WT	15	35	V-0	Non-ANSI (#1)	(#1)	-	-	288	30
Resist coatings for use on Recognized printd wiring boards										
PSR-200/PSG-200 (ASP 1)	GN	10	40	V-0	FR-4.0	0.38	260	3	-	-
	BK	19	40	V-0	FR-4.0	0.38	260 260	3 3	-	-
UVC-II	GN	22	40	V-0	FR-1	1.45	-	-	260	10
UVC-II-G	GN	22	40	V-0	FR-4.0	0.38	-	-	288	20
	GN	8	30	V-0	FR-1	0.71	-	-	280	15
	GN	10	30	V-0	CEM-1	0.63	-	-	288	20

(#1) - Evaluation with Chin-Shi Electronic Materials Ltd (E206580) single-sided (SS) metal base laminate Grade CS-AL-88 (at 0.8mm metal base thickness with 0.060-0.165mm dielectric thickness).

(ASP 1) - Assembly Solder process evaluated to IPC-TM-650, 2.6.27 Thermal Stess Assembly Simulation

Marking: Company name and model designation.

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